THE ESCC POLICY AND STANDARD WORKING GROUP (PSWG)

ESCCON2021

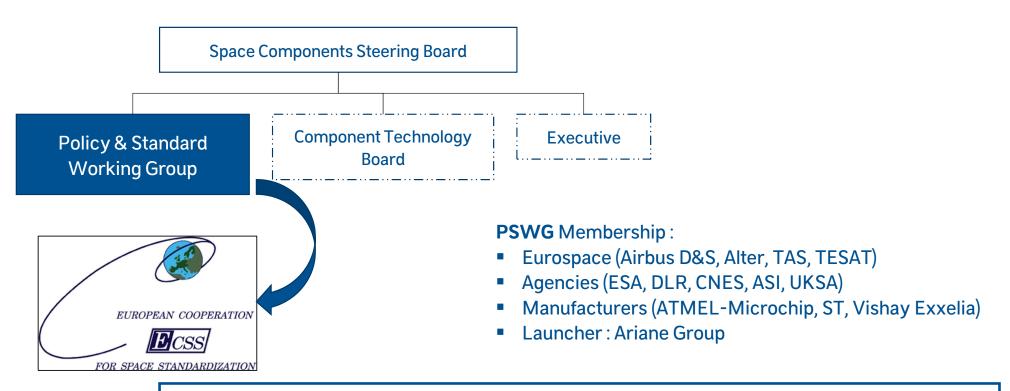
9 - 11 March 2021

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PSWG Organisation & Mission

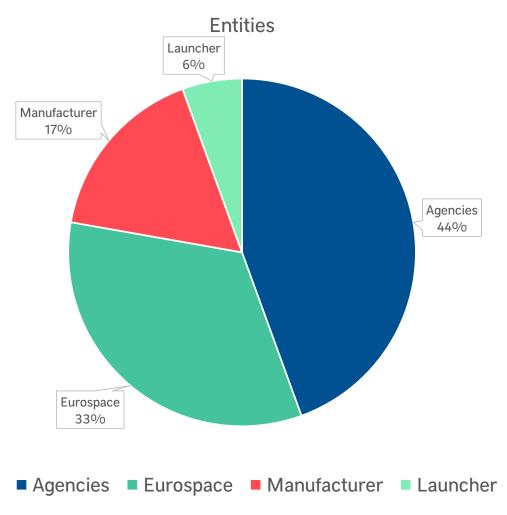


PSWG mainly aims at:

- ✓ Approving new ESCC generic specifications
- ✓ Improving the ECSS standards regarding component procurement



PSWG Members



PSWG Membership:

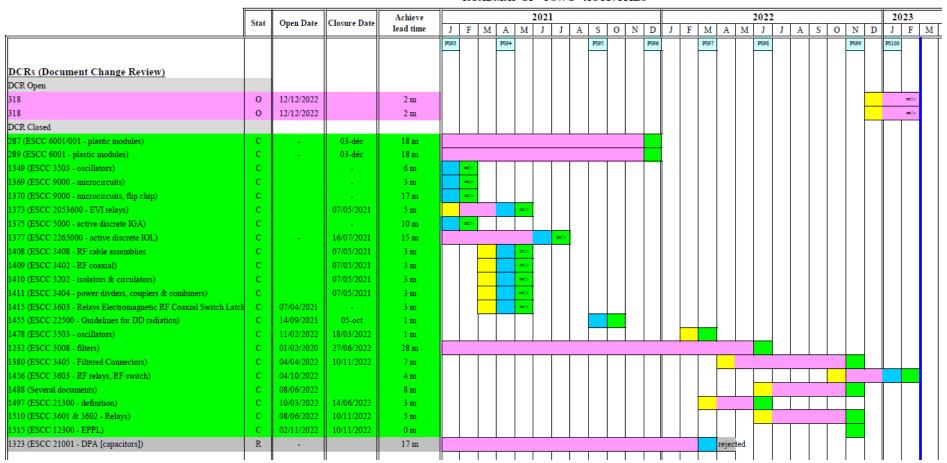
- Eurospace (Airbus D&S, Alter, TAS, TESAT)
- Agencies (ESA, DLR, CNES, ASI, UKSA)
- Manufacturers (ATMEL-Microchip, ST, Vishay, Exxelia)
- Launcher: Ariane Group





Document Change Reviews

ROADMAP OF "PSWG" ACTIVITIES



Accelerating the sequence of activities with the same level of confidence





PSWG Activities

	C4-4	O D-4-	Closure Date	Achieve	2021 2022 2023
	Stat	Open Date	Closure Date	lead time	J F M A M J J A S O N D J F M A M J J F M A M J J A S O N D D A S O N
					PS93 PS94 PS95 PS96 PS97 PS98 PS90 PS100
PSWG activities					
ESCC 9000P (plastic package in ESCC 9000)	0	oct-19		41 m	**
Task Force on Counterfeit parts and shortage of parts	С	09/12/2021	31/03/2022	3 m	
Replacement of ESCC basic specs by MIL test methods	С		-	52 m	=> see DCRs 1369 & 1370
II .		1	11	I	



Noordwijk, 23 March 2022

ESA-TECQE-LE-2022-000974

ESCC Executive Public Notice (EEPN-2022-1 Issue 1)

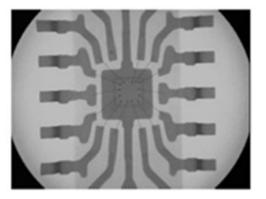
Subject: Counterfeit risk awareness due to global shortage of EEE & PCB

To: European Space Community

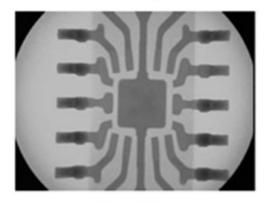




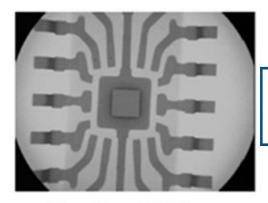
PSWG Activities



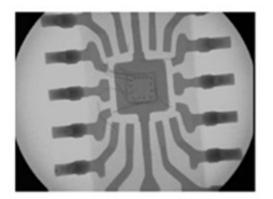
Nearly



No Die



No Bond Wires



No Comment ALTER



Risk Mitigation (list not exhaustive):

- **Analysis of Certificate of Conformity** from the manufacturer.
- Checking of packaging and labels.
- 100% external visual inspection.
- 100% electrical test.
- DPA (adequate sample number)







ESCC9000P: generic specification for space plastic encapsulated microcircuits

- Conderned categories:
 - 1. Monolithic Microcircuits, wire-bonded, plastic encapsulated
 - 2. Monolithic Microcircuits, flip-chip, organic substrate
- The consolidated draft of the generic is approved by PSWG
 - Some tricky points but solutions agreed
 - More than 20 members in the Working Group

A further possibility for the manufacturers: ESCC9000P for SiP?





ESCC 6001: Non-hermetic Memory Module

Built on top of the existing ESCC Process Capability Approval (PCA)

A paradigm shift in the ESCC system



- Modules manufactured with COTS add-ons
- ☐ How to qualify these modules in our system?
 - ✓ Single Phase Qualification
 - ✓ Radiation testing
 - ✓ Requirement for add-on components
 - ✓ Creation of Charts





Already published in December 2021





ECSS Standard: ECSS-Q-ST-60-13 for COTS procurement

3 main topics:

- 1. Authorization of pure tin parts without retinning
- 2. Automotive level recognition
- 3. Commercial passive parts introduction

Main difficulties:

- ✓ How to measure trust in a part?
- ✓ Passive COTS => High diversity of parts technologies.

Ceramic capacitors chips												
Automotive grade	Class 1	Class 2	Class 3	Category	Test type	Sample size	Test Procedure	Specific Test condition				
AEC-Q grd 0/1	X	X	X	Evaluation	Construction Analysis	5	ESCC21001					
AEC-Q grd 0/1	X	Χ	X	Evaluation	Temperature characterization	5	ESCC3009 8.10					
AEC-Q grd 0/1	X			Evaluation	Life Test 2000h	40	ESCC3009 8.6 + 8.9	2000 hours - 2 Un				
AEC-Q grd 0/1	X			Screening	Complete screening	100%	ESCC3009 chart F3					
AEC-Q grd 0/1	Х	Х	X	LAT	DPA	3	ESCC21001					
AEC-Q grd 0/1	Х	Χ		LAT	Life Test 1000h	20	ESCC3009 8.6 + 8.9	1000 hours - 2 Un				

Extract of the ECSS-Q-ST-60-13

Procurement test file for automotive capacitors

✓ Document published in May 2022

However, discussion planned on how to keep this standard up-to-date





ECSS Standard: ECSS-Q-ST-60C rev.4 EEE components

Rev.3 already updated in May 2022 to match ECSS-Q-ST-60-13 rev.1:

- ✓ Update on PPBI
- ✓ List of forbidden EEE components
- ✓ Use of pure tin on a case-by-case basis with risk mitigation
- ✓ EQM components requirement



Working Group in process to propose a new update:

- ✓ Update on FPGA and forbidden families
- ✓ Update on <u>level tables</u> and addition of photonic families
- ✓ DCL Template?
- **√** ..

Draft will soon be opened for public review



New context



1. Readability – trustworthy:

ESCC is a kind of brand. Confidence in the ESCC parts quality shall be high.

2. Parts manufacturer oriented:

ESCC shall support European component suppliers

3. Parts customer oriented:

ESCC shall support space projects by providing innovative and competitive parts and bring added value in the supply chain

To find the right balance between these drivers is a challenge To continue to produce a consistent set of standards

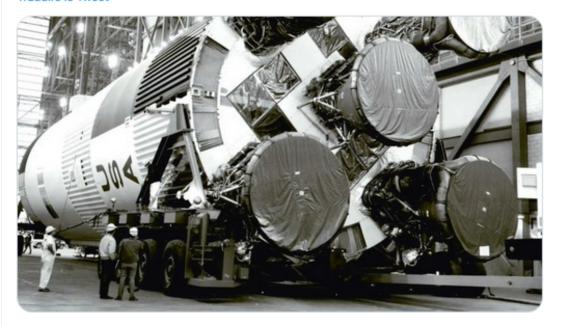


New context



At its peak, the Apollo program was consuming 60% of all chips manufactured in the United States

Traduire le Tweet



3:07 PM · 20 sept. 2022 · Buffer

CHALLENGES



We know what to do

Imaginez que l'humanité a été capable de poser une sonde sur une comète à plus de 500 millions de kilomètres de la Terre et d'obtenir cette

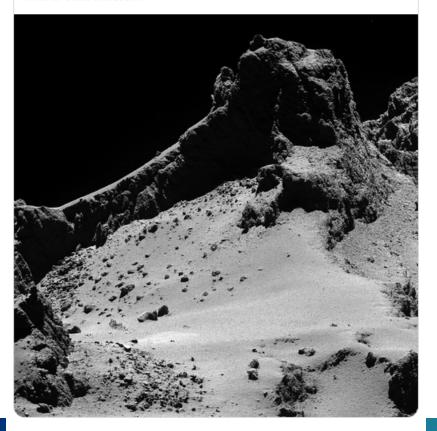
Peut être qu'il y a encore de l'espoir, quand on travaille ensemble on peut faire des choses hallucinantes!



Paul Byrne @ThePlanetaryGuy · 2 mars

This is the surface of a comet.

Afficher cette discussion







13 @ cnes



THANKS FOR YOUR ATTENTION THANKS AS WELL TO THE PSWG MEMBERS